Chips JU Calls in semiconductor technology and opportunities to collaborate with Japan, Taiwan and Singapore

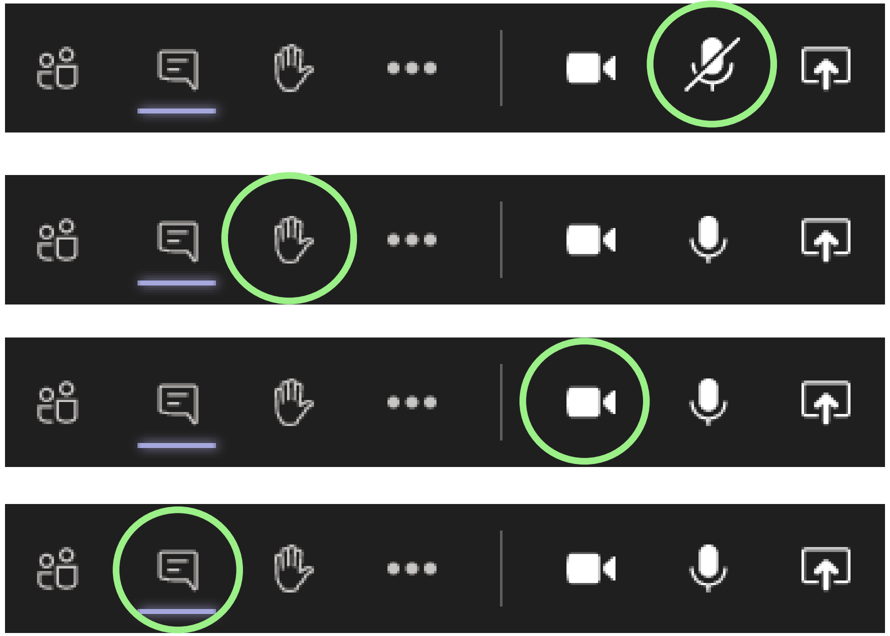
21 May 2026

VINNOVA

Chips JU

Housekeeping rules

- Please keep all microphones muted
- Write your questions in the chat or use the hand-raising function when asking questions in the Q&A session
- Preferably activate your video when asking questions
- No separate chat dialogue out of consideration for the speaker
- Presentation will be shared on our homepage for Chips JU calls 2026
- No recording, no AI Note Taker allowed



Agenda

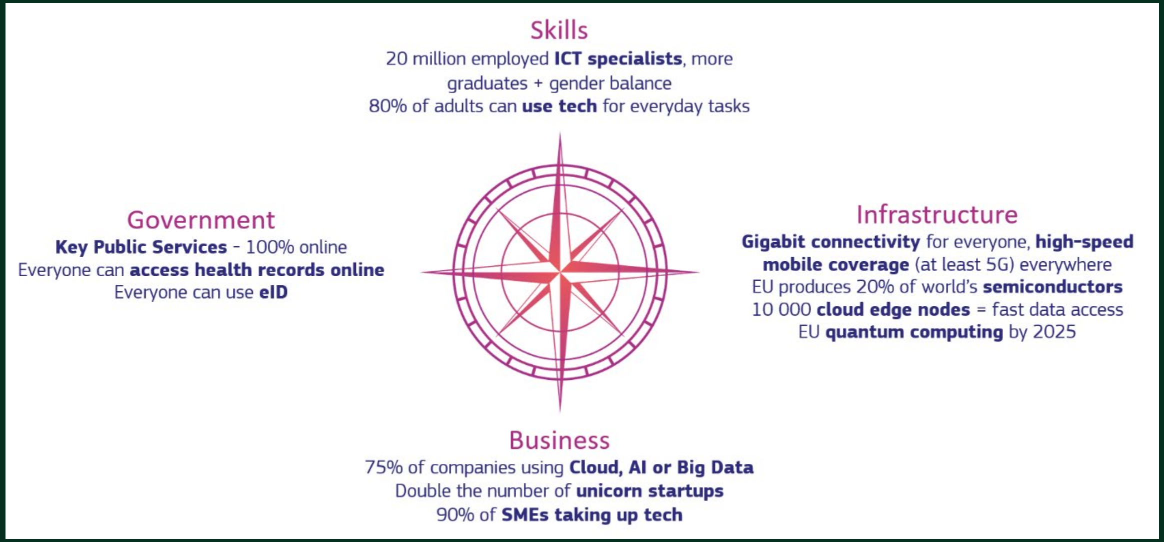
- EU Digital Decade
- The European partnership Chips Joint Undertaking
- Work Programme 2026
  - Overview
  - International collaboration call - EU and Japan on semiconductors
  - International collaboration - call with Digital Partnership and TTC countries
- National Rules (Sweden, Japan, Taiwan, Singapore)
- Testimony - SweGaN
- Q&A
- Upcoming events & additional calls (Eureka)
- ECS Collaboration Tool

Swedish delegation in Chips JU

- Chips JU governance: Governing Board (GB) and Public Authorities Board (PAB)
- Delegation:
  - Adela Saavedra Granholm, PAB Vice-chair, alternate GB
  - Lars Gustafsson, main delegate GB, alternate PAB
  - Sverker Brundin, alternate PAB & GB
  - Jessica Svennebring, alternate PAB & GB
- National contact point (NCP) Horizon Europe, cluster 4: Jeannette Spühler

Digital Decade targets for 2030

Strategy



Skills

20 million employed **ICT specialists**, more graduates + gender balance
80% of adults can **use tech** for everyday tasks

Government

Key Public Services - 100% online
Everyone can **access health records online**
Everyone can use **eID**

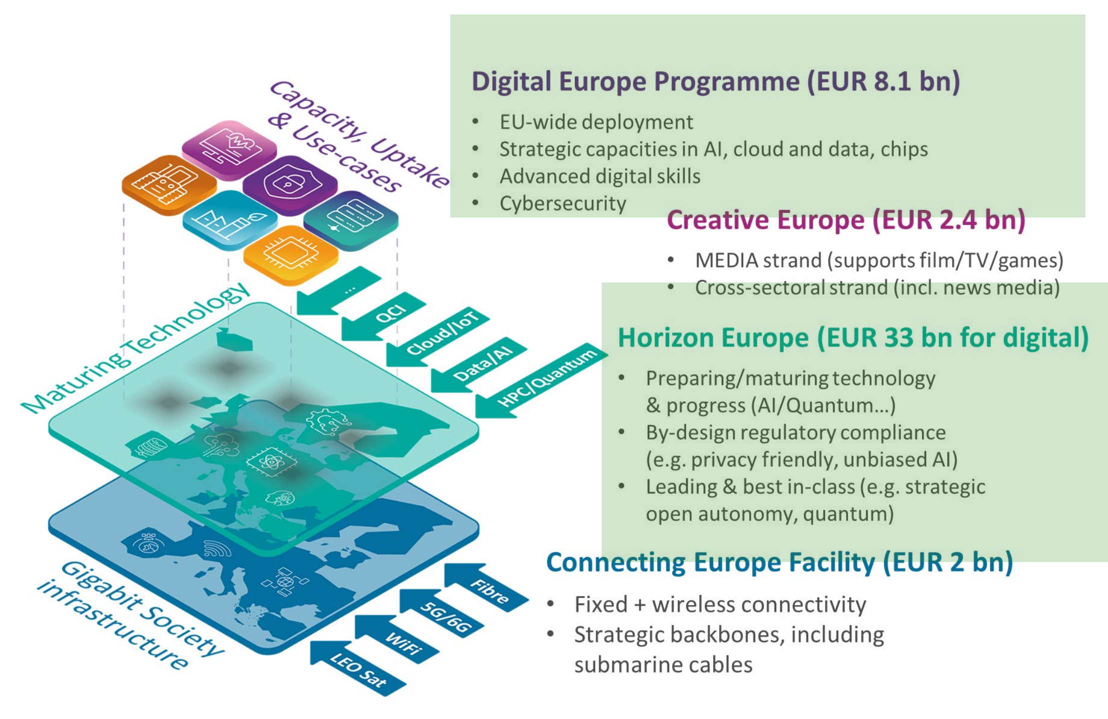
Infrastructure

Gigabit connectivity for everyone, **high-speed mobile coverage** (at least 5G) everywhere
EU produces 20% of world's **semiconductors**
10 000 **cloud edge nodes** = fast data access
EU **quantum computing** by 2025

Business

75% of companies using **Cloud, AI or Big Data**
Double the number of **unicorn startups**
90% of **SMEs taking up tech**

Funding programmes



Digital Europe Programme (EUR 8.1 bn)

- EU-wide deployment
- Strategic capacities in AI, cloud and data, chips
- Advanced digital skills
- Cybersecurity

Creative Europe (EUR 2.4 bn)

- MEDIA strand (supports film/TV/games)
- Cross-sectoral strand (incl. news media)

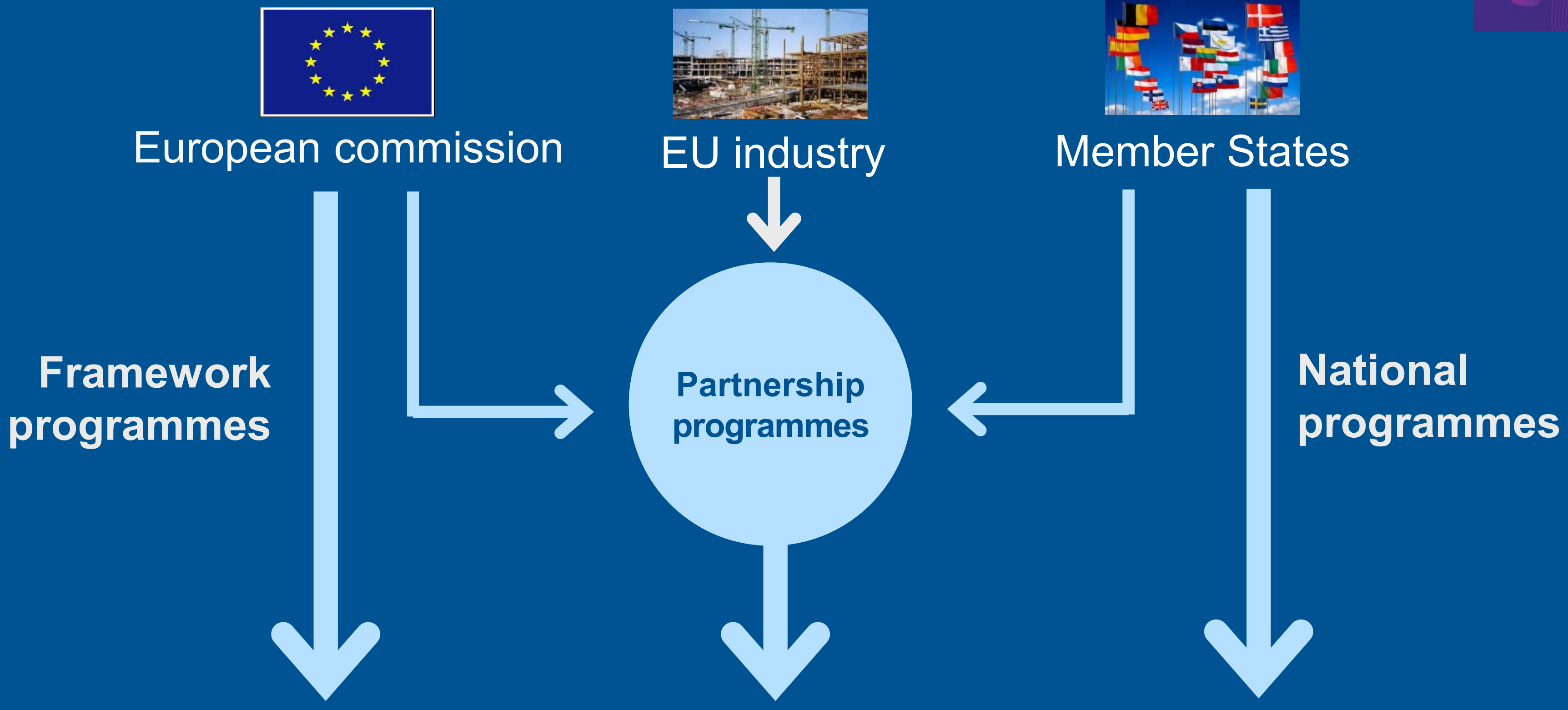
Horizon Europe (EUR 33 bn for digital)

- Preparing/maturing technology & progress (AI/Quantum...)
- By-design regulatory compliance (e.g. privacy friendly, unbiased AI)
- Leading & best in-class (e.g. strategic open autonomy, quantum)

Connecting Europe Facility (EUR 2 bn)

- Fixed + wireless connectivity
- Strategic backbones, including submarine cables

European partnerships



European commission

EU industry

Member States

Framework programmes

Partnership programmes

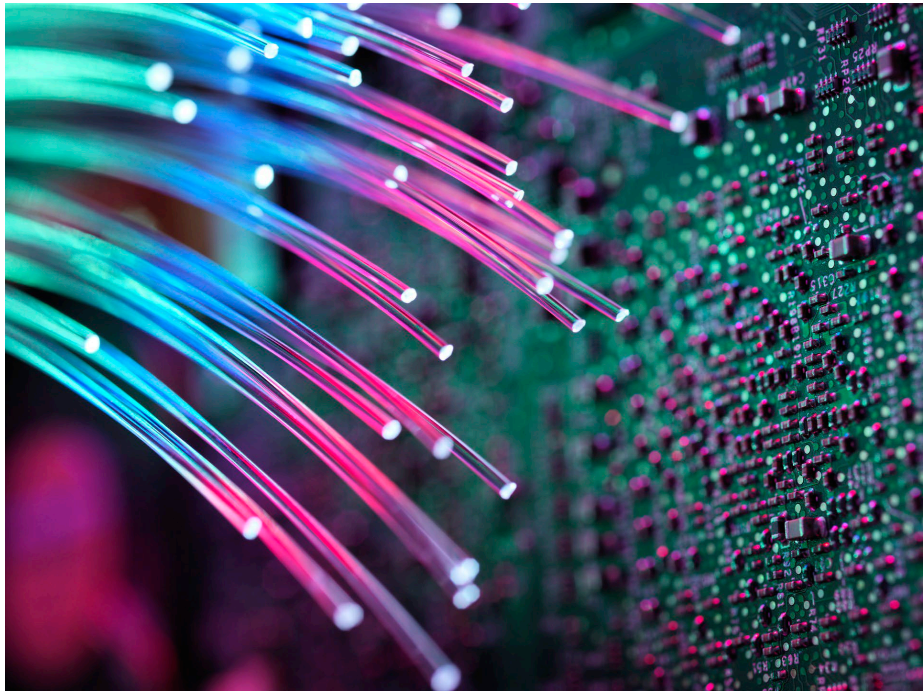
National programmes

Research project

Chips Joint Undertaking

Home · Chips JU

European Partnership Programme – Electronics Components and Systems (ECS)



General Objectives: broad actions in electronics

- Reinforce EU strategic autonomy in electronic components and systems
- Establish EU scientific excellence and innovation leadership
- Ensure that components and systems technologies address Europe’s societal and environmental challenges

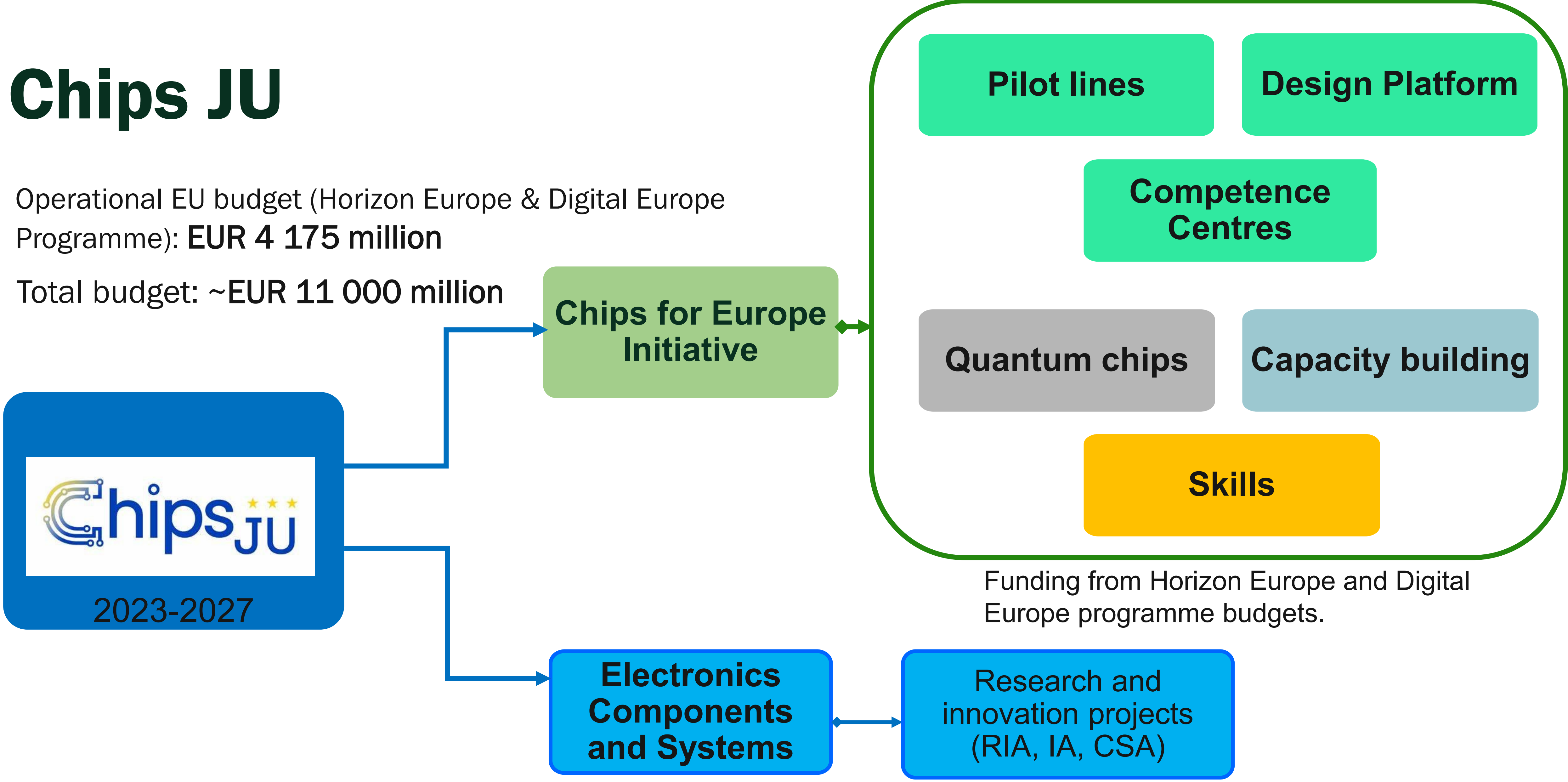
Actions in Chips for Europe initiative

- Pilot lines
- Design platform
- Competence centers
- Quantum chips technology
- Skills and capacity building actions

Chips JU

Operational EU budget (Horizon Europe & Digital Europe Programme): **EUR 4 175 million**

Total budget: ~**EUR 11 000 million**



2023-2027

Chips for Europe Initiative

Pilot lines

Design Platform

Competence Centres

Quantum chips

Capacity building

Skills

Funding from Horizon Europe and Digital Europe programme budgets.

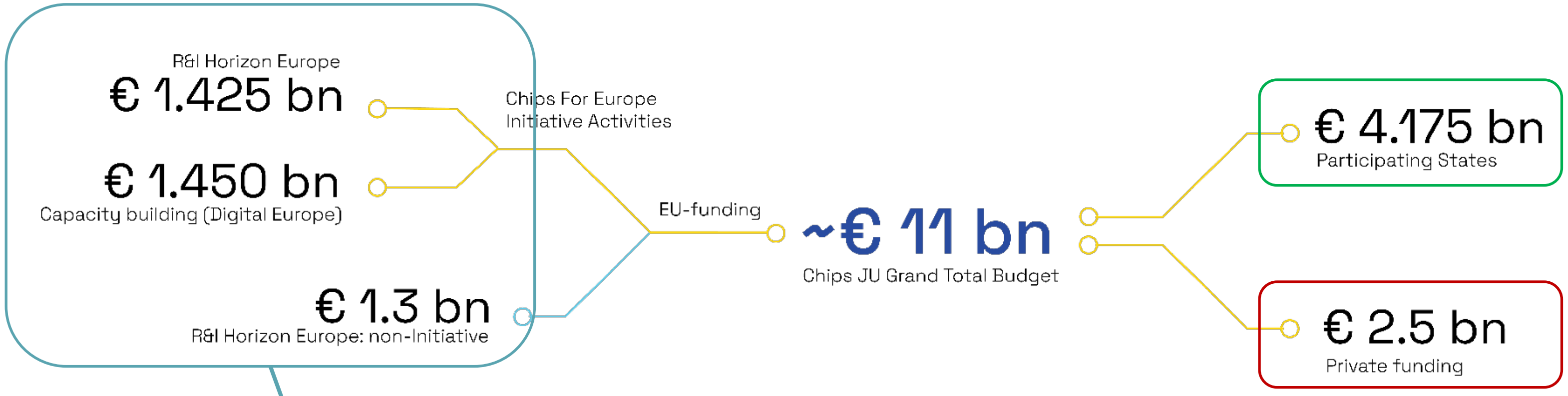
Electronics Components and Systems

Research and innovation projects (RIA, IA, CSA)

Research and innovation cooperation projects

Funding from Horizon Europe programme budget

CHIPS JU



R&I Horizon Europe
€ 1.425 bn

€ 1.450 bn
Capacity building (Digital Europe)

€ 1.3 bn
R&I Horizon Europe: non-Initiative

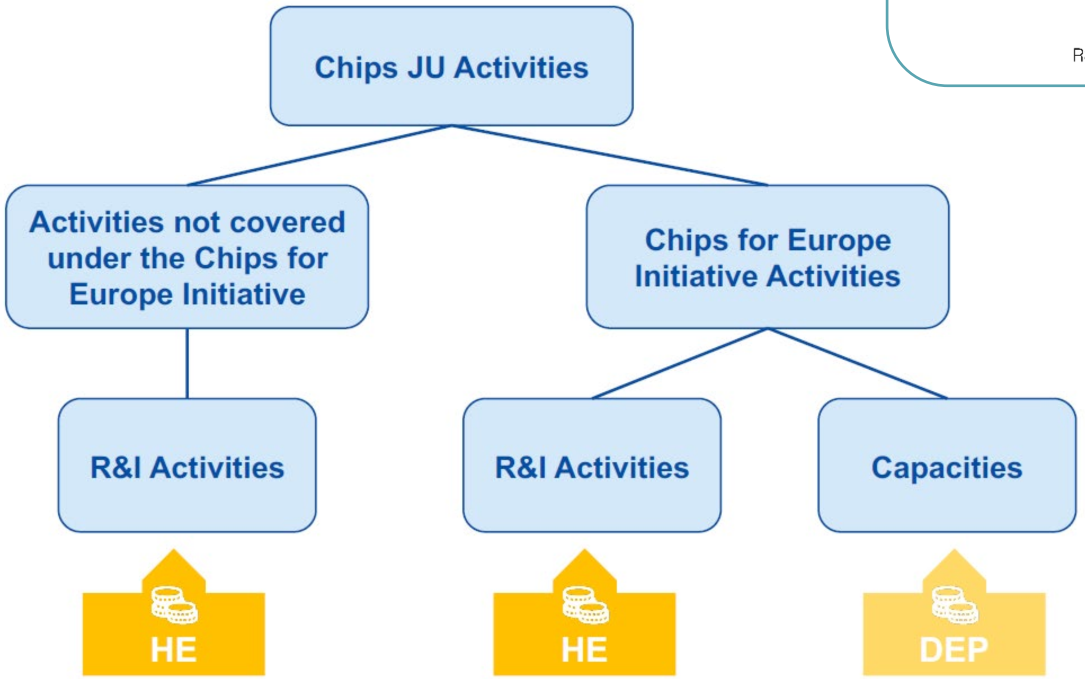
Chips For Europe Initiative Activities

EU-funding

~€ 11 bn
Chips JU Grand Total Budget

€ 4.175 bn
Participating States

€ 2.5 bn
Private funding



Chips JU Activities

Activities not covered under the Chips for Europe Initiative

Chips for Europe Initiative Activities

R&I Activities

R&I Activities

Capacities

HE

HE

DEP

EU Contribution to Chips JU (excl	Chips for Europe Initiative	Electronic Components and Systems	Total
R&I (Horizon Europe)	1.425	1.300	2.725
Cap building (DEP)	1.450	n.a.	1.450
Total	**2.875**	**1.300**	**4.175**

Work Programme 2026

Chips JU

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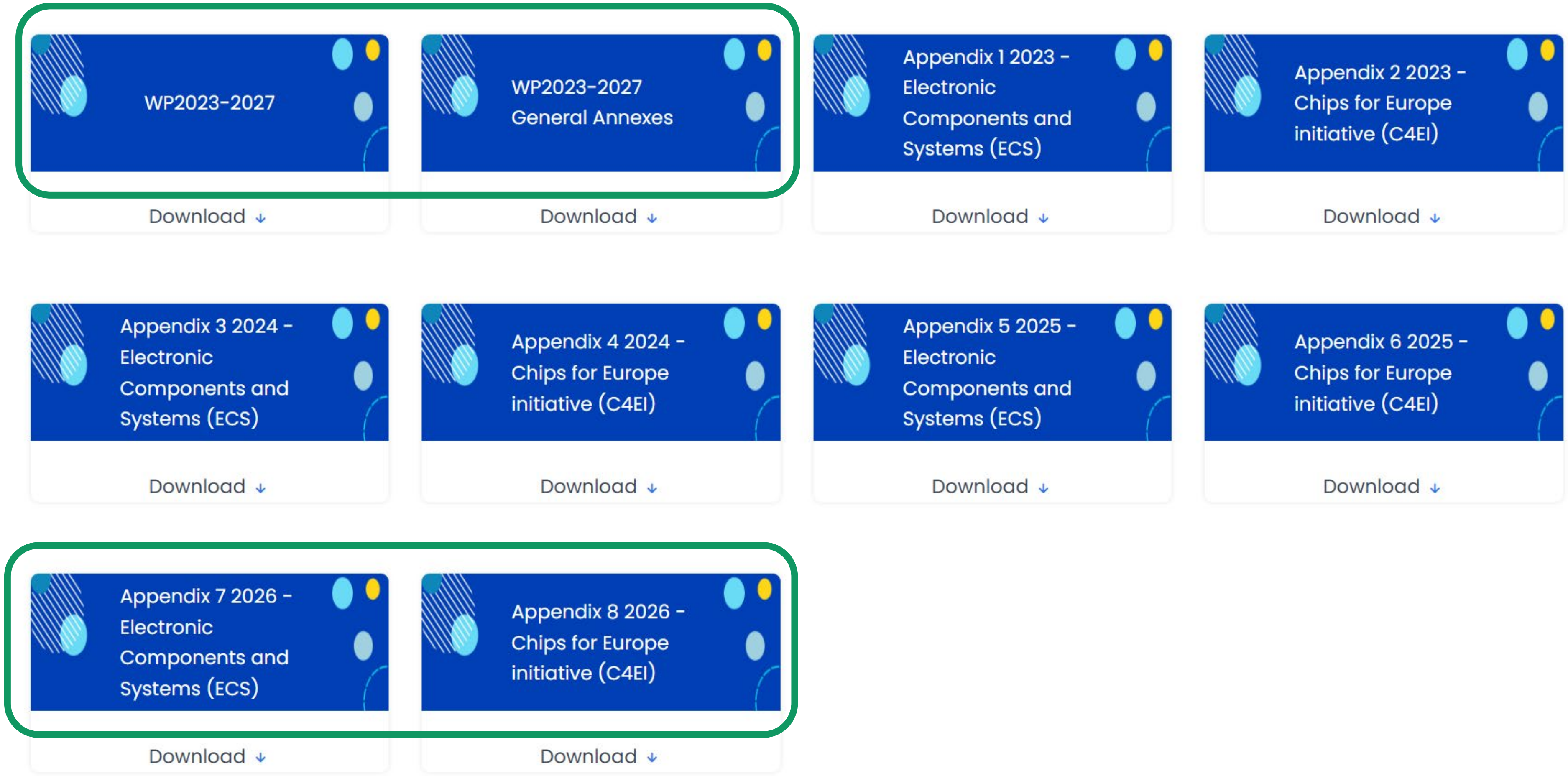
Work Programme 2026

- Multiannual Work Programme 2023-2027
- Multiannual Work Programme 2023-2027 GENERAL ANNEXES
- Appendix 7 2026 – Electronics Components and Systems (ECS)
- Appendix 8 2026 – Chips for Europe Initiative (C4EI)

Multiannual Work Programme 2023-2027 · Chips Ju



WP2023-2027
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WP2023-2027 General Annexes
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Appendix 1 2023 - Electronic Components and Systems (ECS)
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Appendix 2 2023 - Chips for Europe initiative (C4EI)
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Appendix 3 2024 - Electronic Components and Systems (ECS)
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Appendix 4 2024 - Chips for Europe initiative (C4EI)
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Appendix 5 2025 - Electronic Components and Systems (ECS)
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Appendix 6 2025 - Chips for Europe initiative (C4EI)
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Appendix 7 2026 - Electronic Components and Systems (ECS)
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Appendix 8 2026 - Chips for Europe initiative (C4EI)
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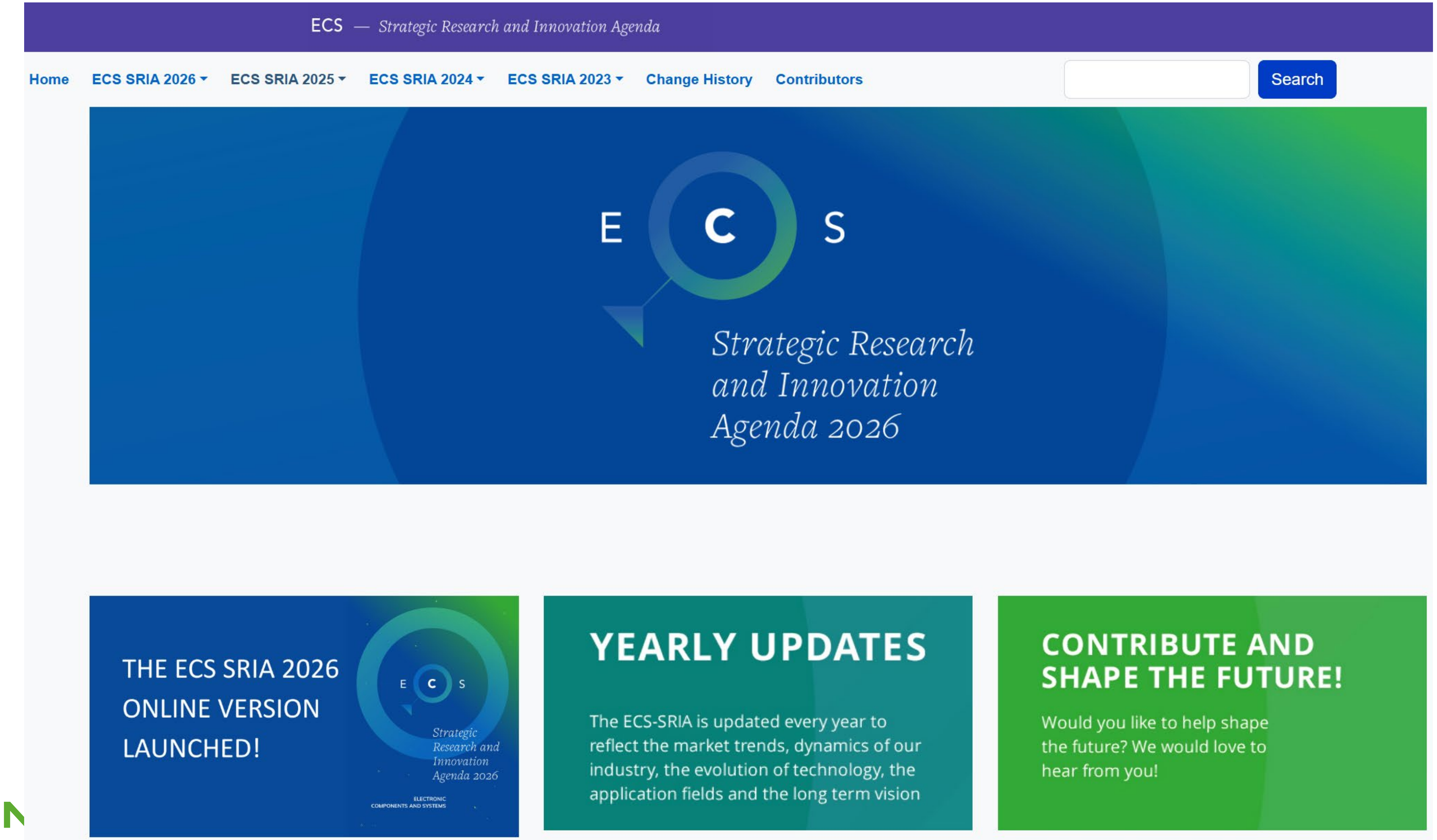
Strategic Research and Innovation Agenda 2026

- Programmets strategiska agenda: ECS SRIA 2026 | ECS SRIA



ECS — *Strategic Research and Innovation Agenda*

Strategic Research and Innovation Agenda 2026

THE ECS SRIA 2026 ONLINE VERSION LAUNCHED!

YEARLY UPDATES

The ECS-SRIA is updated every year to reflect the market trends, dynamics of our industry, the evolution of technology, the application fields and the long term vision

CONTRIBUTE AND SHAPE THE FUTURE!

Would you like to help shape the future? We would love to hear from you!

International collaboration call - EU and Japan on semiconductors

- **Topic: DIGITAL-JU-Chips-2026-SG-JAPAN**
- Scope:
  - Develop methods for chiplet co-optimization, interface design, and 2.5D/3D integration processes, including through-silicon vias, interposers, and bonding techniques.
  - Engage material scientists, chemical engineers, semiconductor manufacturers, and AI experts to bridge research and industrial applications, supporting broad adoption and commercial viability.
  - Proposals should encourage partnerships across **industry, academia, and research organizations** to foster breakthroughs in semiconductor manufacturing and contribute to advancing global semiconductor standards.
  - Technology Readiness Levels 5-7
- EU-budget: 5 miljoner € SE-budget: 10 miljoner kr
- Chips JU can only fund organisations in the Chips JU participating states.

International collaboration call - EU and Japan on semiconductors

- Topic: DIGITAL-JU-Chips-2026-SG-JAPAN
- Expected Outcomes:
  - Advanced heterogeneous integration, particularly in 2.5D and 3D packaging, to support AI functionalities.
  - Standardised chiplet interfaces, enabling interoperability and fostering a dynamic chiplet ecosystem.

- Proposed projects should demonstrate solutions across laboratory and pilot environments, with verification in semiconductor manufacturing use cases.
- Proposals also need to facilitate knowledge transfer and promote stakeholder engagement through industry workshops, publications, and networking events.
- Participant eligibility conditions are described in Annex 2 “DIGITAL EUROPE PROGRAMME conditions” of the WP General Annexes.

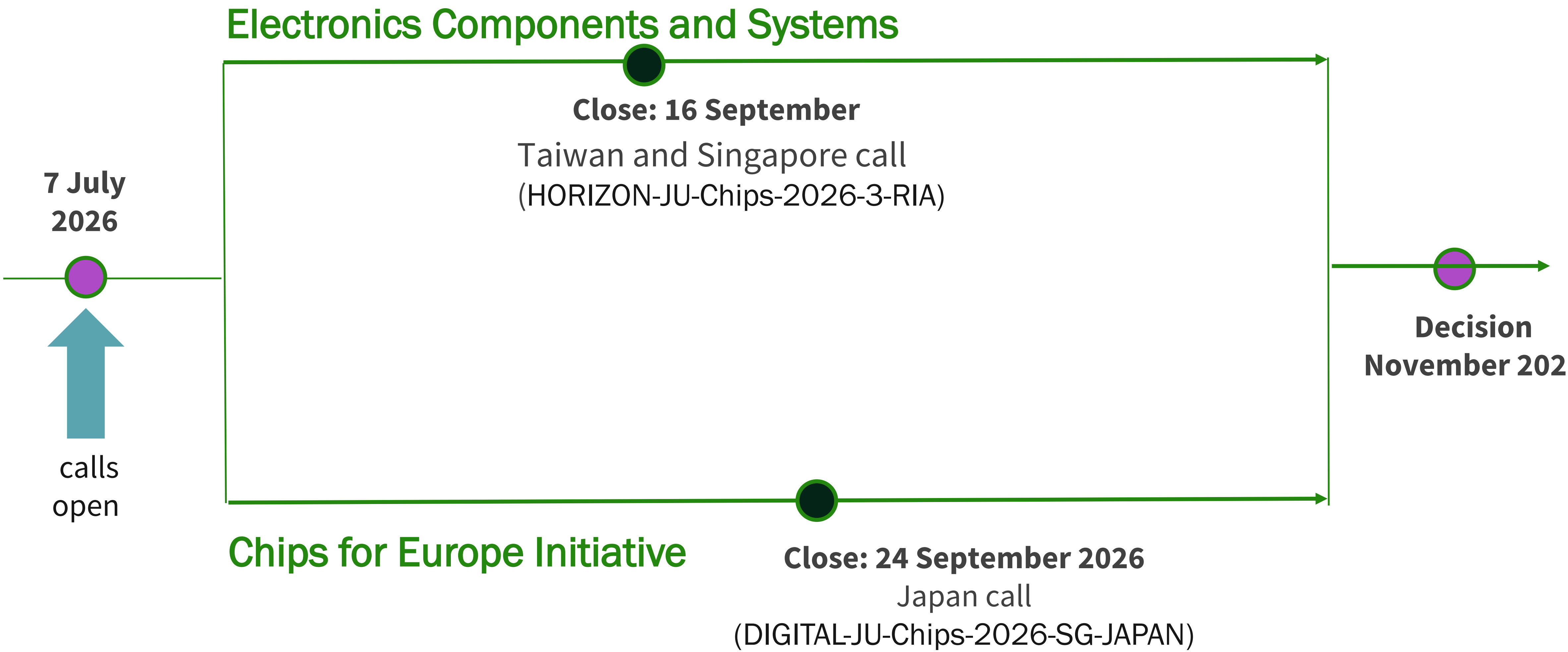
International collaboration - Call with Digital Partnership and TTC countries

- **Topic: HORIZON-JU-Chips-2026-3-RIA**
- Scope (Taiwan, Singapore):
  - Address research reaching **TRL 4** with **high potential not yet demonstrated** in the **design**, **fabrication** process and/or **packaging** segments of the micro-nano-electronics and integration technologies value chain.
  - Focus innovation on **materials**, **physical concepts** or **device** architecture building on **neuromorphic** or integration technologies.
- EU-budget: 5 miljoner €

International collaboration - Call with Digital Partnership and TTC countries

- Topic: HORIZON-JU-Chips-2026-3-RIA
- Expected Outcomes
  - Innovative design and integration concepts for neuromorphic computing systems supporting very low energy consumption, connectivity, embedded functions for mobile applications.
  - Alternative manufacturing process technologies for semiconductor chips including frontend or backend for heterogenous integration.
  - Very advanced packaging solutions aiming heterogeneous integration of multiple functions and materials.

Timeline



7 July 2026

calls open

Electronics Components and Systems

Close: 16 September

Taiwan and Singapore call

(HORIZON-JU-Chips-2026-3-RIA)

Chips for Europe Initiative

Close: 24 September 2026

Japan call

(DIGITAL-JU-Chips-2026-SG-JAPAN)

Decision

November 2026

National Rules

Important:

Japan: DIGITAL-JU-Chips-2026-SG-JAPAN

- transitional phase to be associated to Horizon Europe – pillar II
- Call with Japan is allocated under Digital Europe Programme, Japan is not associated to Digital Europe Programme

Taiwan and Singapore:HORIZON-JU-Chips-2026-3-RIA

- Call allocated under Horizon Europe
- Not associated to Horizon Europe

- National complementary funding
- Multinational calls

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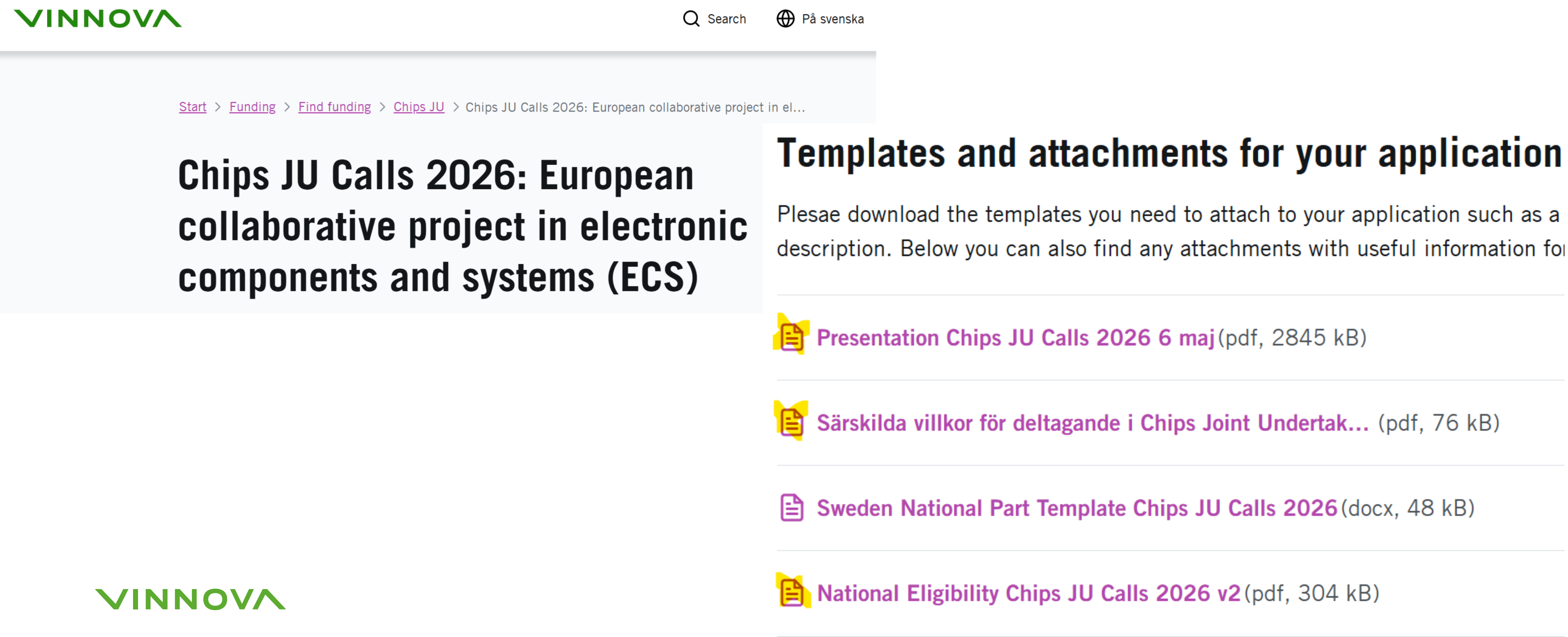
Sweden

- The Swedish national rules are published at Vinnova’s webbsite for Chips JU Calls 2026: [European collaborative projects in electronic components and systems | Vinnova]



[Start] > [Funding] > [Find funding] > [Chips JU] > Chips JU Calls 2026: European collaborative project in el...

Chips JU Calls 2026: European collaborative project in electronic components and systems (ECS)

Templates and attachments for your application

Plesae download the templates you need to attach to your application such as a description. Below you can also find any attachments with useful information fo

- **Presentation Chips JU Calls 2026 6 maj** (pdf, 2845 kB)
- **Särskilda villkor för deltagande i Chips Joint Undertak...** (pdf, 76 kB)
- **Sweden National Part Template Chips JU Calls 2026** (docx, 48 kB)
- **National Eligibility Chips JU Calls 2026 v2** (pdf, 304 kB)

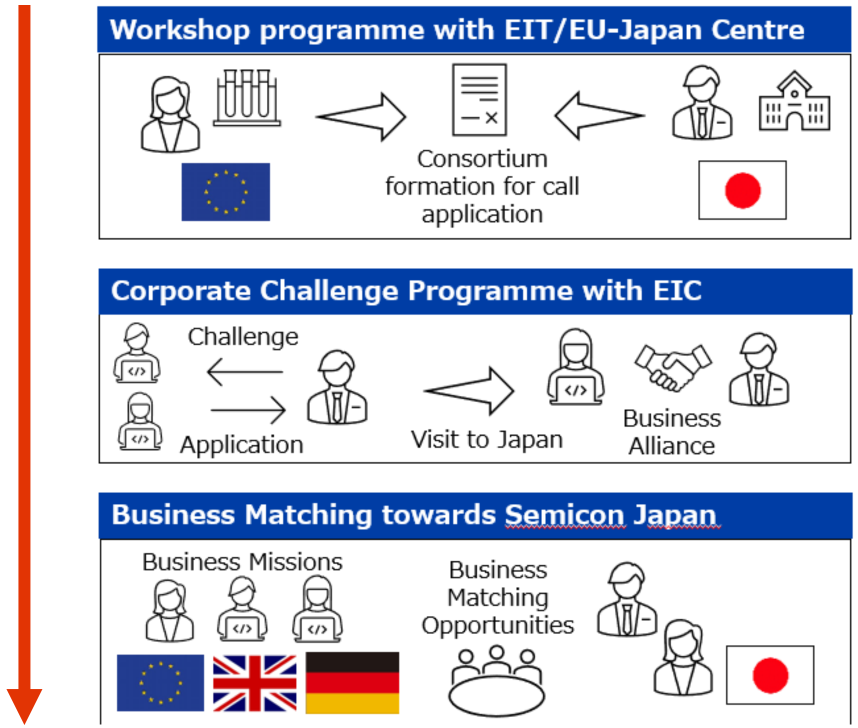
Japan

JETRO

ldn_invest@jetro.go.jp

JETRO Europe Innovation

TRL



Workshop programme with EIT/EU-Japan Centre

Consortium formation for call application

Corporate Challenge Programme with EIC

Challenge

Application

Visit to Japan

Business Alliance

Business Matching towards Semicon Japan

Business Missions

Business Matching Opportunities

[Research Excellence, Industrial Strategy and International Collaboration - Top Scientist Lecture on Semiconductors]()

EU-Japan Centre
for Industrial Cooperation
一般財団法人日欧産業協力センター

https://www.eu-japan.eu/

[NCP Japan]()

Important:

- Japan: transitional phase to be associated to Horizon Europe
- Call with Japan is allocated under Digital Europe Programme

DIGITAL-JU-Chips-2026-SG-JAPAN

Share experience and Possible partnering event

Contact jeannette.spuhler@vinnova.se

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Taiwan

- Taiwanese companies that are invited by European partners to participate in Horizon Europe projects may apply for government funding support from Taiwan's Ministry of Economic Affairs (MOEA), under the International Innovation R&D Cooperation Program
- https://service.moea.gov.tw/EE514/tw/aiip/185.html

Information Sharing on Singapore-Horizon Europe Complementary Fund

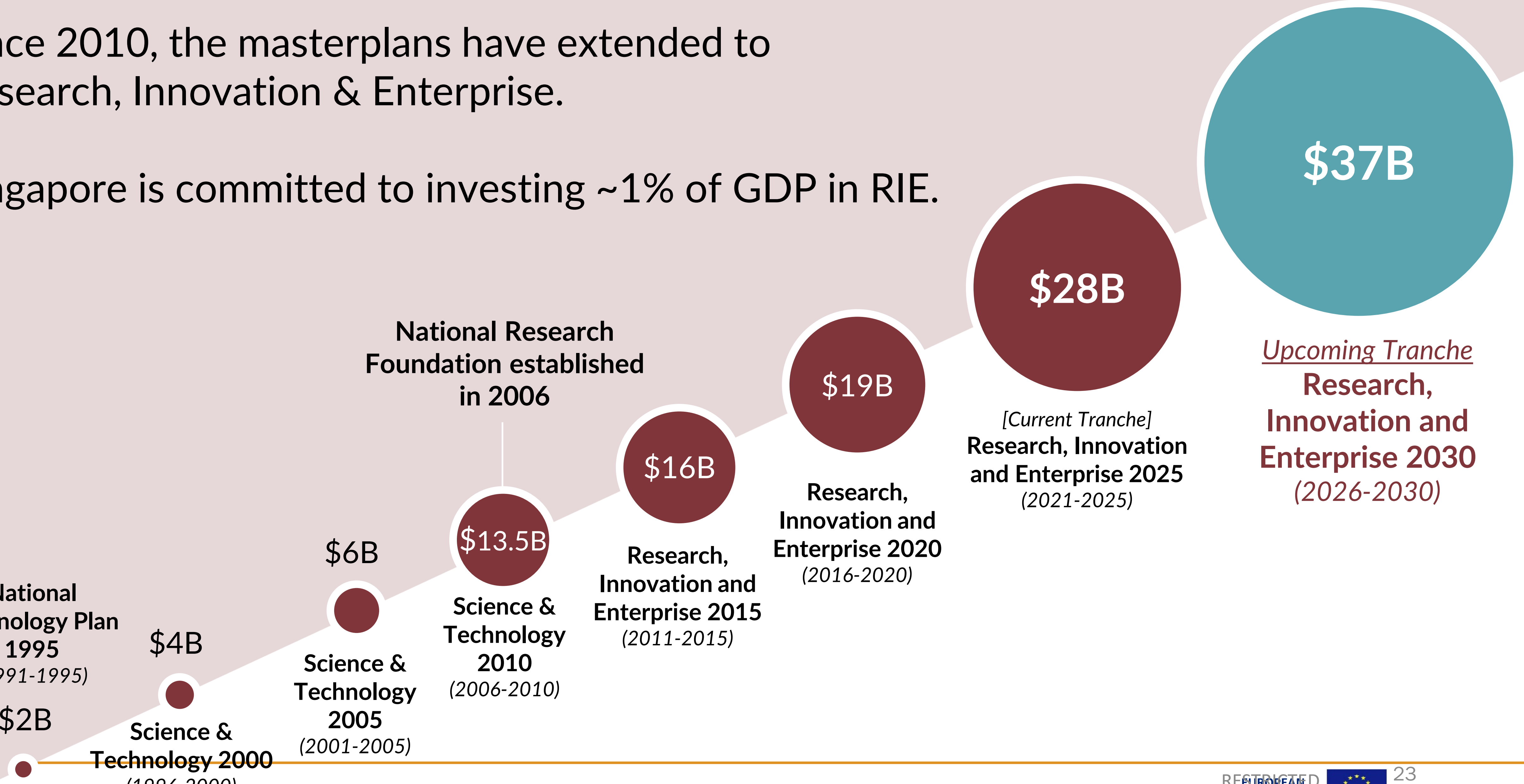
21 May 2026

NATIONAL RESEARCH FOUNDATION
PRIME MINISTER'S OFFICE
SINGAPORE

Singapore has had 7 Science & Technology Masterplans over 3 Decades

Since 2010, the masterplans have extended to Research, Innovation & Enterprise.

Singapore is committed to investing ~1% of GDP in RIE.



$2B

National Technology Plan 1995
(1991-1995)

$4B

Science & Technology 2000
(1996-2000)

$6B

Science & Technology 2005
(2001-2005)

National Research Foundation established in 2006

$13.5B

Science & Technology 2010
(2006-2010)

$16B

Research, Innovation and Enterprise 2015
(2011-2015)

$19B

Research, Innovation and Enterprise 2020
(2016-2020)

$28B

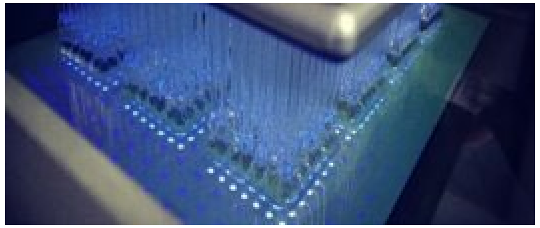
[Current Tranche]
Research, Innovation and Enterprise 2025
(2021-2025)

$37B

Upcoming Tranche
Research, Innovation and Enterprise 2030
(2026-2030)

Singapore’s RIE efforts are organised as 4 Domains and 2 Horizontals

Manufacturing, Trade and Connectivity (MTC)



Strengthen Singapore as a global business and innovation hub for advanced manufacturing and connectivity

Human Health and Potential (HHP)

Transform and protect health, advance human potential and create economic value

Urban Solutions and Sustainability (USS)

Renew and build a liveable, resilient, sustainable and economically vibrant city for tomorrow

Smart Nation and Digital Economy (SNDE)

Develop technology leadership to drive our Smart Nation ambition, and anchor Singapore as a trusted digital innovation hub

Academic Research

Build a robust base of research capabilities and peaks of international excellence

Talent

Nurture a strong research and innovation talent base

Supported by **Innovation and Research Translation**

Accelerate value realisation and capture

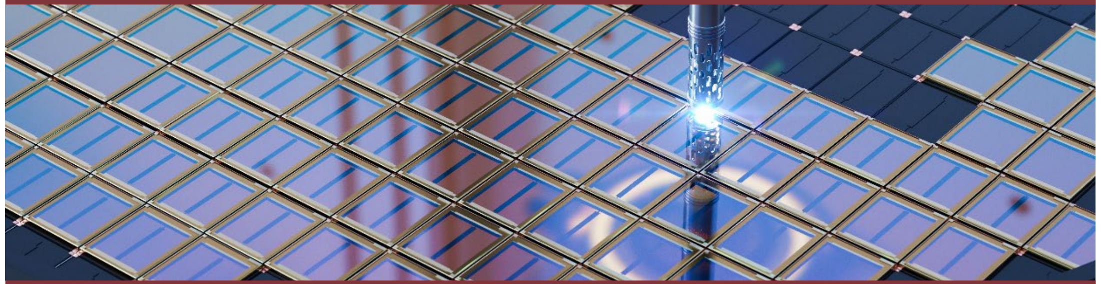
RIE2030 will aim to drive greater outcomes in priority areas.

In RIE2030, we will:

1. Sharpen our focus on creating value and impact, with heightened ambitions in selected strategic areas
2. Sustain investments in our focus areas
3. Keep our basic research capabilities and talent at the cutting edge

We will address key economic and national priorities through RIE Flagships and Grand Challenges.

RIE Flagships: Economic Value Creation



Semiconductor

Build on Singapore's global R&D leadership to establish Singapore as a strategically important R&D node in the semiconductor industry.

RIE Grand Challenges: National Strategic Priorities

Maximising Healthy and Successful Longevity

Address challenges and opportunities in our ageing population through research and translation, with a focus on maintaining brain health and physical function as people age.

The second RIE Flagship and RIE Grand Challenge will be announced at a later juncture.

Singapore-Horizon Europe (SG-HE) Complementary Fund

Singapore-Horizon Europe (SG-HE) Complementary Fund

What is the Singapore-Horizon Europe (SG-HE) Complementary Fund?

It is a unilateral funding arrangement by Singapore, administered by the National Research Foundation (NRF) of Singapore. The fund supports research or activities conducted in Singapore, by eligible Singapore entities that participate in Horizon Europe Pillar II projects in priority areas for Singapore.

How will this Fund affect participation by Singapore entities?

There is now an option for Singapore entities to apply to the SG-HE Complementary Fund, if they wish to receive funding support for participation in Horizon Europe Pillar II projects, if assessed to be eligible and the research is aligned with Singapore's RIE priorities.

- Singapore entities can receive in-principle approval of funding support from NRF, if their SG-HE Complementary fund application is considered supportable.

- Singapore entities can receive funding support from NRF, once their Horizon Europe Pillar II proposal has undergone evaluation and the project is awarded to their consortium.

Scope of Funding

What can the SG-HE Complementary Fund support?

Applicants may apply for SG-HE Complementary Fund Support to participate in Horizon Europe Pillar II Actions (Grant Calls) launching in 2026-2027, under the following Thematic Clusters and Missions.

Thematic Clusters*	Thematic Cluster 1: Health Thematic Cluster 3: Civil Security for Society^ Thematic Cluster 4: Digital Industry and Space Thematic Cluster 5: Climate, Energy and Mobility Thematic Cluster 6: Food, Bioeconomy, Natural Resources, Agriculture and Environment
Missions	Adaptation to Climate Change, Cancer, Healthy Oceans, Seas, Coastal and Inland Waters, Climate-neutral and Smart Cities, Soil Health and Food
Actions (Grant Calls)	Research and Innovation Actions (RIA) Innovation Actions (IA) Coordination and Support Actions (CSA)

*Thematic Cluster 2: Culture, Creativity and Inclusive Society falls outside the scope of funding.
^For Thematic Cluster 3: Where the scope of the grant call meets Singapore's national strategic priorities. Applicants should check with NRF before submitting proposals.

Eligible Applicants

Researchers from Publicly Funded Research Institutions

- Institutions include Autonomous Universities (AUs), A*STAR research institutes, CREATE entities, polytechnics, public healthcare institutions, and their affiliated research institutes.
- Researchers must be accomplished PIs with track record of leadership ability, hold a primary/joint appointment with the institution (9 months per year in Singapore), or have an existing residency commitment in Singapore. They are expected to have a reasonable time commitment to the project.

Companies

- Registered and operating in Singapore, a governance structure that is compliant with requirements specified by NRF, at least 30% local shareholding, and financial viability to start and complete the project.
- Must partner with a publicly funded research institute in Singapore, which will serve as the host institute.

Funding Support Rates

Singapore Entities	Direct Cost Support	Indirect Cost Support
Researchers from Publicly-Funded Research Institutions	100%	25% of Direct Costs
Companies	*SMEs – 50% Larger than SME – 30%	Indirect Costs are not supported

*SMEs are companies with group annual sales turnover not exceeding S$100 million, or a group employment base of no more than 200 employees.

Thank You

Upcoming events and calls

- EU Business Hub @ Semicon Japan 2026, 7 - 11 Dec 2026; EU Business Hub @ Semicon Japan 2026 | EU Business Hub

  The EU Business Hub @ Semicon Japan 2026 Business Mission, taking place from 7-11 December 2026, is your gateway to the forefront of innovation in Japan.

  If you want to learn more about this Business Mission join online EU Info Day Wednesday the 10th of June 10:00AM CEST.

  Deadline for application: 11 September 2026
- Semiconductor Delegation to Japan 2026 - Business Sweden
- Eureka calls
  - With Singapore: https://www.vinnova.se/e/utlysning-2026-00974/eureka-utlysning-inom-bioteknik/ deadline 30th september
  - With Taiwan and Singapore: https://www.vinnova.se/e/utlysning-2026-00974/eureka-globalstars-utlysning-med-taiwan/, deadline 22 September

ECS collaboration tool

- ECS Collaboration Tool
- https://een.ec.europa.eu/partners

About the ECS Collaboration Tool

The ECS Collaboration Tool is a powerful networking platform that enables experts in Electronic Components and Systems to create project proposals, find partners, and access funding opportunities, all in one place.

Create a Project Idea
Start your project and invite collaborators.

Find Partners
Search for partners based on expertise.

Browse Ideas
Explore project ideas and join teams.

Message Board
Post messages to attract partners.

Contacts:

- Adela Saavedra Granholm, adela.saavedragranholm@vinnova.se
- Lars Gustafsson, lars.gustafsson@vinnova.se
- Sverker Brundin, sverker.brundin@vinnova.se
- Jeannette Spühler, jeannette.spuhler@vinnova.se

Thank you!

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Sweden's Innovation Agency